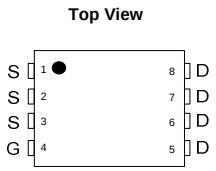
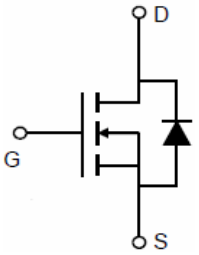
# FNK N-Channel Enhancement Mode Power MOSFET

## Description

The FNK06NS04E uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

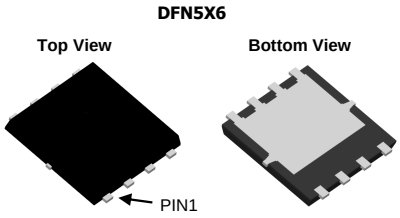



**Schematic diagram**

## General Features

- $V_{DS}$ = 60V,$I_D$ =110A
  $R_{DS(ON)}$ < 3.3mΩ @ $V_{GS}$=10V (Typ:2.5mΩ)
  $R_{DS(ON)}$ < 4.9mΩ @ $V_{GS}$=4.5V (Typ:3.8mΩ)
- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Low gate to drain charge to reduce switching losses




## Application

- Power switching application
- Load switch

## Package Marking and Ordering Information

| Device Marking | Device | Device Package | Reel Size | Tape width | Quantity |
|---|---|---|---|---|---|
| FNK06NS04E | FNK06NS04E | DFN5*6-8L | - | - | - |

## Absolute Maximum Ratings ($T_C$=25℃unless otherwise noted)

| Parameter | Symbol | Limit | Unit |
|---|---|---|---|
| Drain-Source Voltage | $V_{DS}$ | 60 | V |
| Gate-Source Voltage | $V_{GS}$ | ±20 | V |
| Drain Current-Continuous | $I_D$ | 110 | A |
| Drain Current-Continuous($T_C$=100℃) | $I_D$ (100℃) | 72 | A |
| Pulsed Drain Current | $I_{DM}$ | 440 | A |
| Maximum Power Dissipation | $P_D$ | 160 | W |
| Operating Junction and Storage Temperature Range | $T_J$,$T_{STG}$ | -55 To 175 | ℃ |

## Thermal Characteristic

| | | | |
|---|---|---|---|
| Thermal Resistance,Junction-to-Case(Note 2) | $R_{\theta JC}$ | 0.93 | ℃/W |

## Electrical Characteristics ($T_C$=25℃unless otherwise noted)

| Parameter | Symbol | Condition | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|
| **Off Characteristics** | | | | | | |
| Drain-Source Breakdown Voltage | $BV_{DSS}$ | $V_{GS}$=0V $I_D$=250μA | 60 | | - | V |

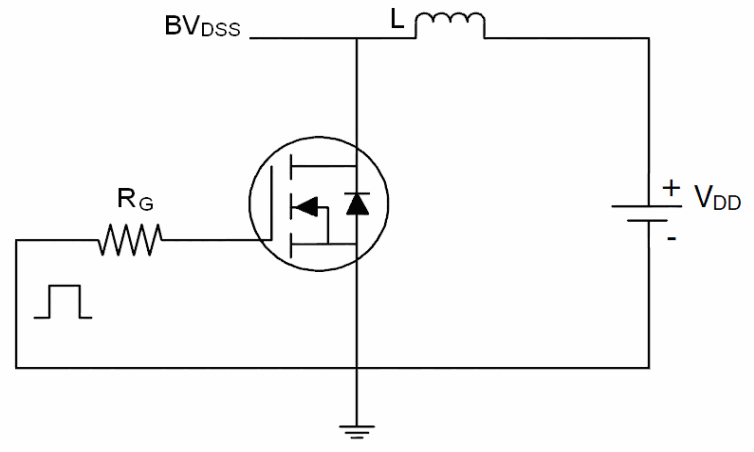
| | | | | | | |
|---|---|---|---|---|---|---|
| Zero Gate Voltage Drain Current | $I_{DSS}$ | $V_{DS}$=60V,$V_{GS}$=0V | - | - | 1 | μA |
| Gate-Body Leakage Current | $I_{GSS}$ | $V_{GS}$=±20V,$V_{DS}$=0V | - | - | ±100 | nA |
| **On Characteristics** (Note 3) | | | | | | |
| Gate Threshold Voltage | $V_{GS(th)}$ | $V_{DS}$=$V_{GS}$,$I_D$=250μA | 1.4 | 2.0 | 2.5 | V |
| Drain-Source On-State Resistance | $R_{DS(ON)}$ | $V_{GS}$=10V, $I_D$=10A | - | 2.5 | 3.3 | mΩ |
| | | $V_{GS}$=4.5V, $I_D$=10A | - | 3.8 | 4.9 | mΩ |
| Forward Transconductance | $g_{FS}$ | $V_{DS}$=5V,$I_D$=9A | 25 | - | - | S |
| **Dynamic Characteristics** (Note4) | | | | | | |
| Input Capacitance | $C_{lss}$ | $V_{DS}$=25V,$V_{GS}$=0V, F=1.0MHz | - | 4355 | - | PF |
| Output Capacitance | $C_{oss}$ | | - | 2215 | - | PF |
| Reverse Transfer Capacitance | $C_{rss}$ | | - | 245 | - | PF |
| **Switching Characteristics** (Note 4) | | | | | | |
| Turn-on Delay Time | $t_{d(on)}$ | $V_{DD}$=30V, $R_L$=1Ω $V_{GS}$=10V,$R_{GEN}$=3Ω | - | 8.5 | - | nS |
| Turn-on Rise Time | $t_r$ | | - | 6 | - | nS |
| Turn-Off Delay Time | $t_{d(off)}$ | | - | 30 | - | nS |
| Turn-Off Fall Time | $t_f$ | | - | 5 | - | nS |
| Total Gate Charge | $Q_g$ | $V_{DS}$=30V,$I_D$=20A, $V_{GS}$=10V | - | 58 | - | nC |
| Gate-Source Charge | $Q_{gs}$ | | - | 8 | - | nC |
| Gate-Drain Charge | $Q_{gd}$ | | - | 17 | - | nC |
| **Drain-Source Diode Characteristics** | | | | | | |
| Diode Forward Voltage (Note 3) | $V_{SD}$ | $V_{GS}$=0V,$I_S$=20A | - | - | 1.2 | V |
| Diode Forward Current (Note 2) | $I_S$ | | - | - | 45 | A |
| Reverse Recovery Time | $t_{rr}$ | TJ = 25°C, IF=20A di/dt = 100A/μs (Note3) | - | 30 | - | nS |
| Reverse Recovery Charge | Qrr | | - | 44 | - | nC |

## Notes:

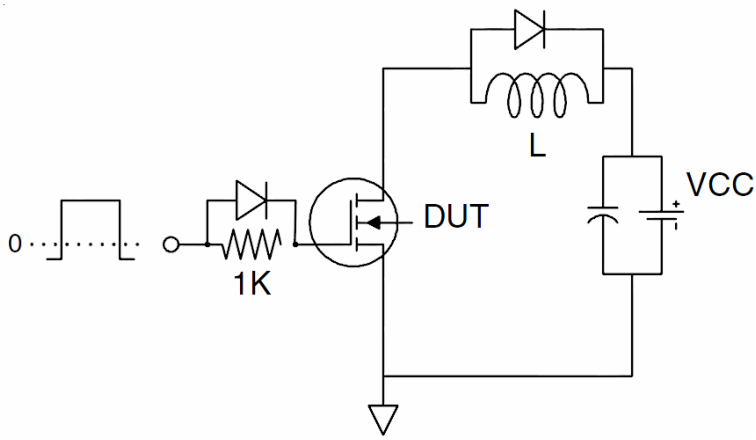
**1.** Repetitive Rating: Pulse width limited by maximum junction temperature.
**2.** Surface Mounted on FR4 Board, t ≤ 10 sec.
**3.** Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
**4.** Guaranteed by design, not subject to production

## Test Circuit

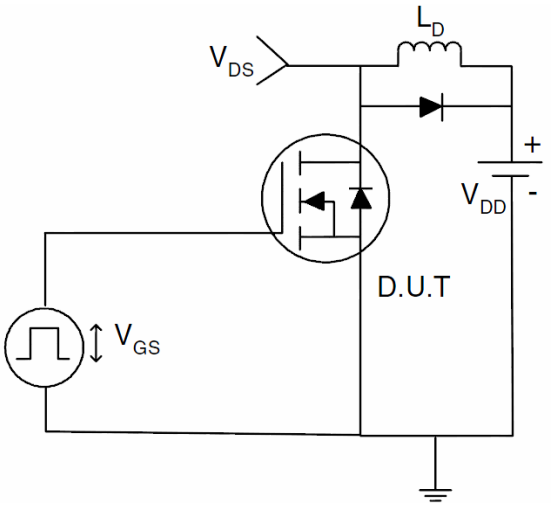
### 1) $E_{AS}$ test Circuit




### 2) Gate charge test Circuit




### 3) Switch Time Test Circuit



## Typical Electrical and Thermal Characteristics (Curves)

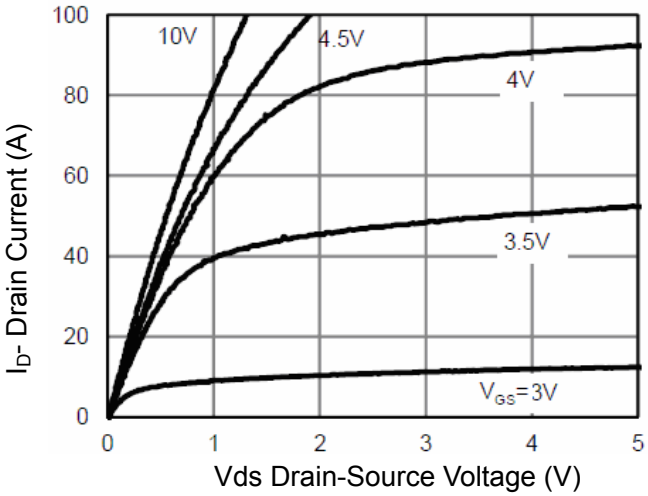



**Figure 1 Output Characteristics**

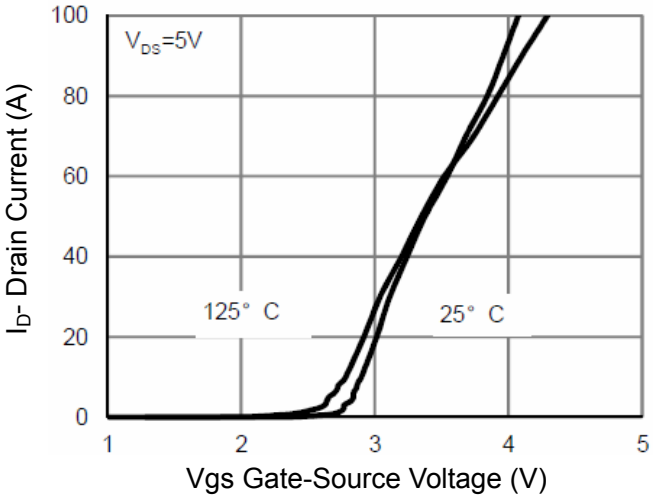



**Figure 2 Transfer Characteristics**

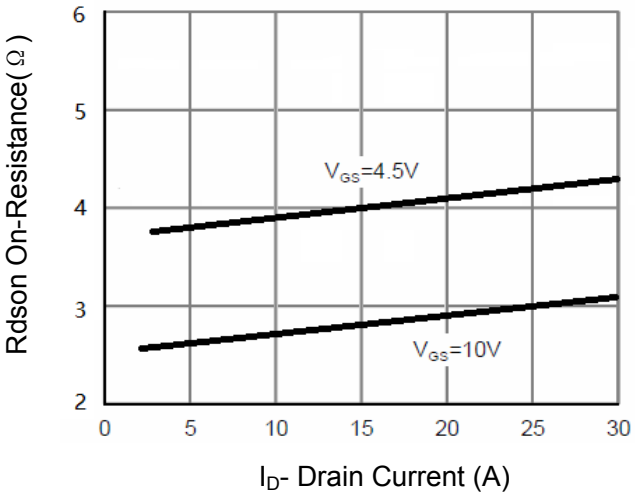



**Figure 3 Rdson- Drain Current**

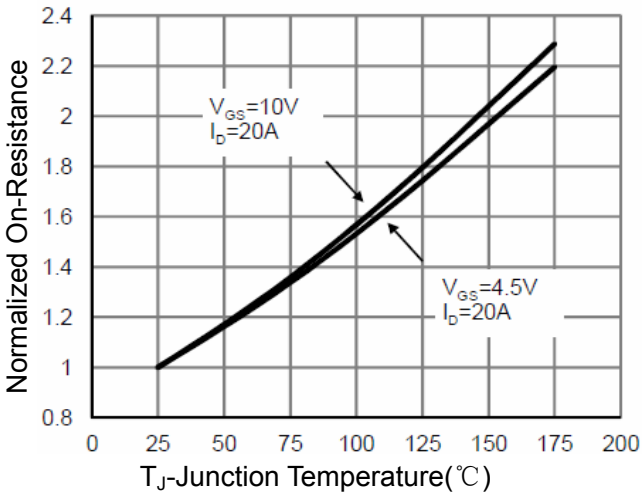



**Figure 4 Rdson-JunctionTemperature**

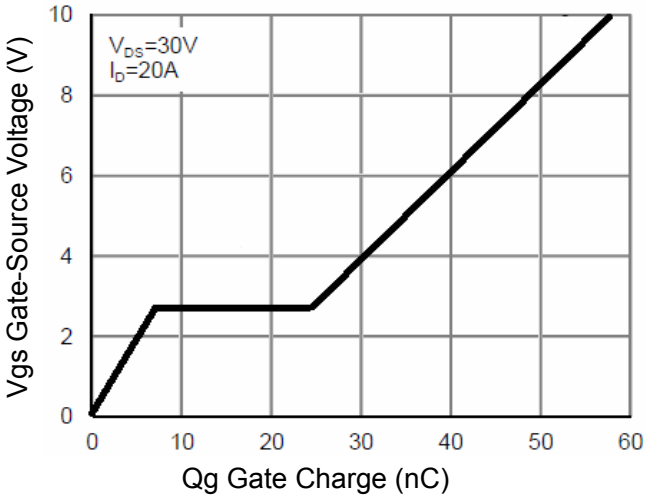



**Figure 5 Gate Charge**

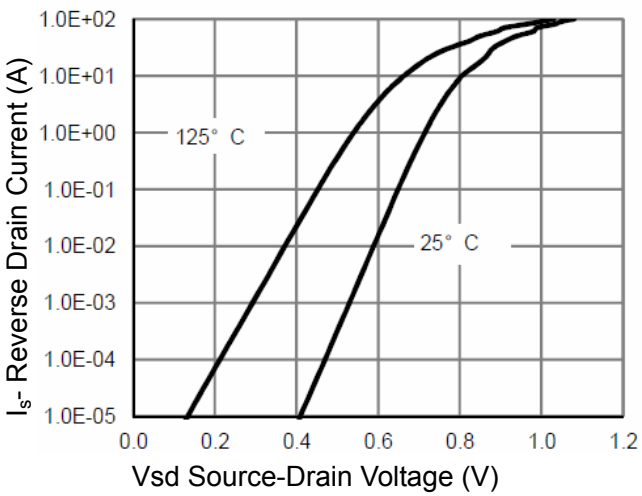



**Figure 6 Source- Drain Diode Forward**

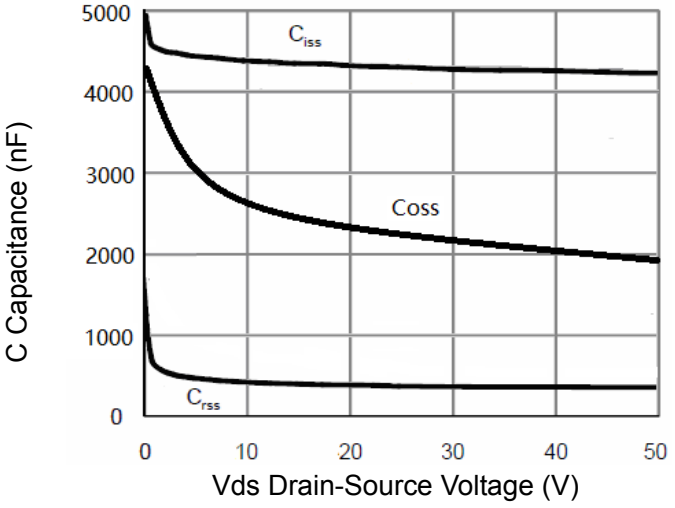



**Figure 7 Capacitance vs Vds**

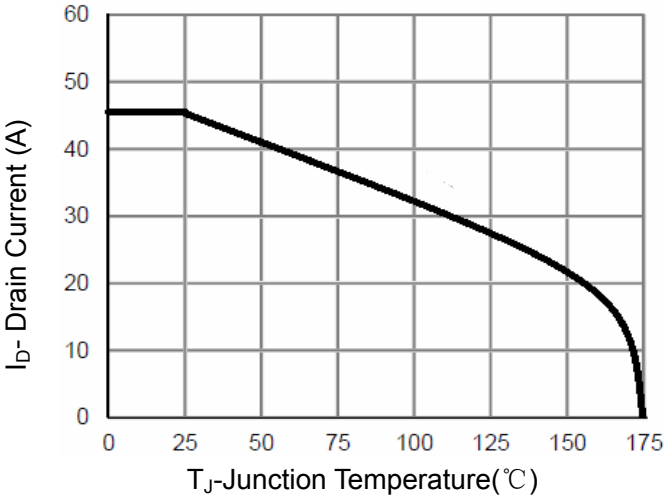



**Figure 9 Current De-rating**

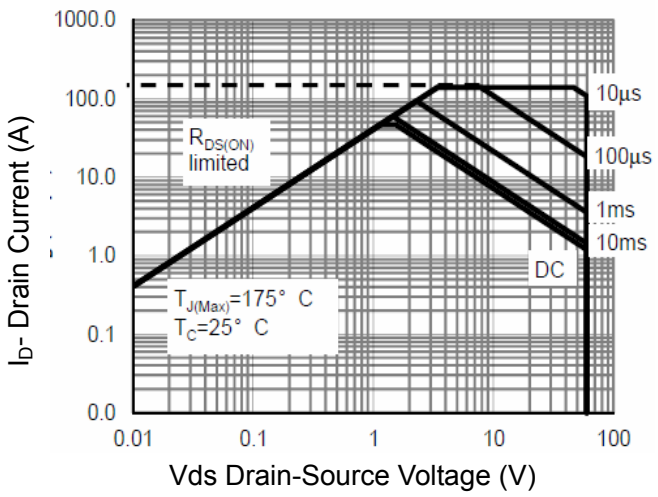



**Figure 8 Safe Operation Area**

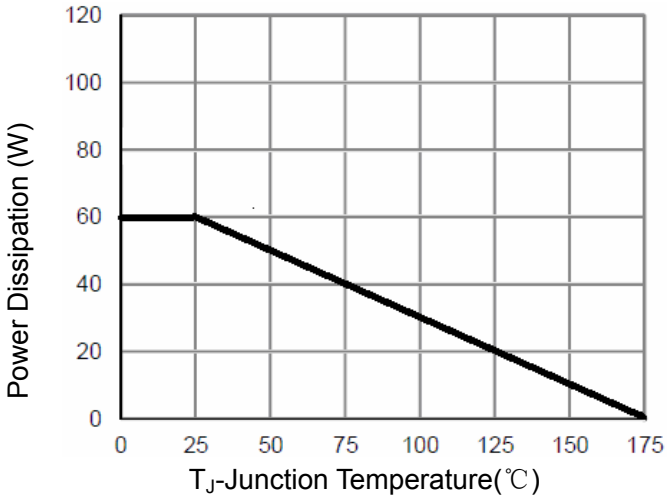



**Figure 10 Power De-rating**

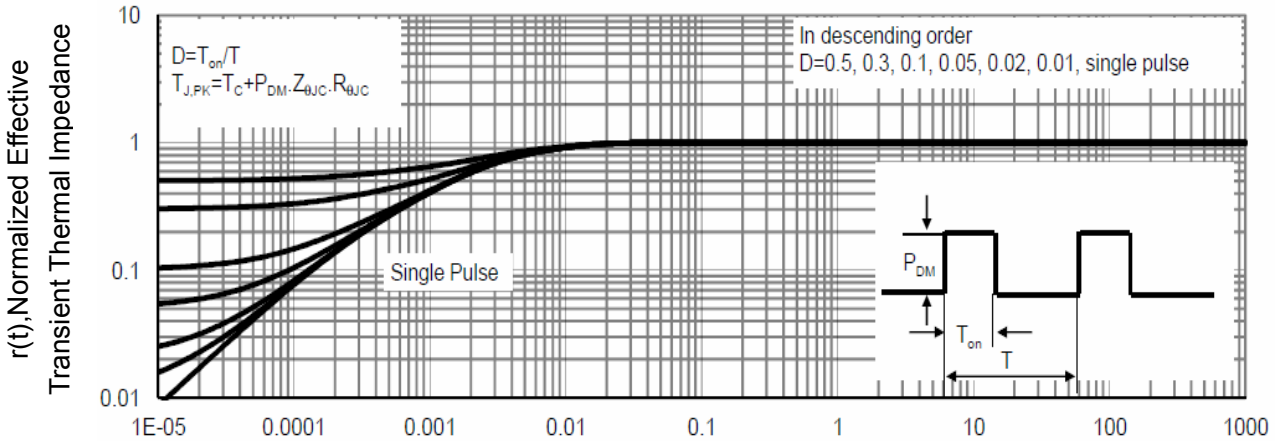
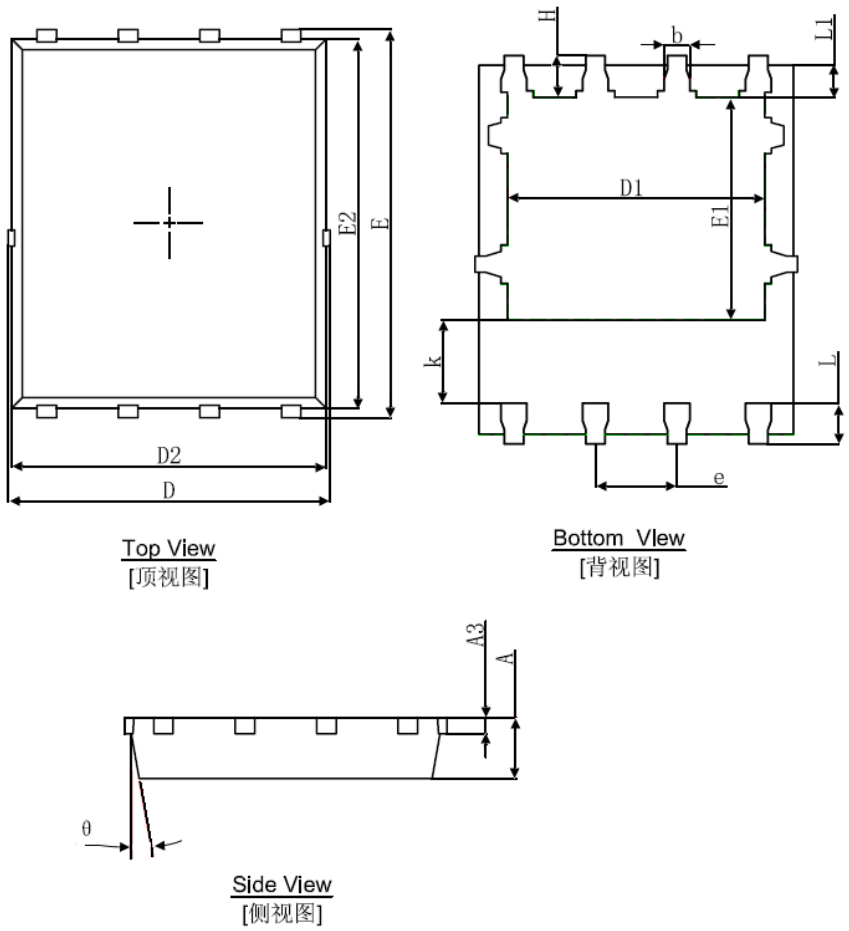



**Figure 11 Normalized Maximum Transient Thermal Impedance**

## DFN5X6-8L Package Information




Top View
[顶视图]

Bottom View
[背视图]

Side View
[侧视图]

| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|---|---|---|---|---|
| | Min. | Max. | Min. | Max. |
| A | 0.900 | 1.000 | 0.035 | 0.039 |
| A3 | 0.254REF. | | 0.010REF. | |
| D | 4.944 | 5.096 | 0.195 | 0.201 |
| E | 5.974 | 6.126 | 0.235 | 0.241 |
| D1 | 3.910 | 4.110 | 0.154 | 0.162 |
| E1 | 3.375 | 3.575 | 0.133 | 0.141 |
| D2 | 4.824 | 4.976 | 0.190 | 0.196 |
| E2 | 5.674 | 5.826 | 0.223 | 0.229 |
| K | 1.190 | 1.390 | 0.047 | 0.055 |
| b | 0.035 | 0.450 | 0.014 | 0.018 |
| e | 1.270(TYP.) | | 0.050(TYP.) | |
| L | 0.559 | 0.711 | 0.022 | 0.028 |
| L1 | 0.424 | 0.576 | 0.017 | 0.023 |
| H | 0.574 | 0.726 | 0.023 | 0.029 |
| θ | 8° | 12° | 8° | 12° |

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